

Operational Amplifiers

Low Noise Operational Amplifiers

BA4560xxx BA4560Rxxx BA4564RFV BA4564WFV

General Description

BA4560xxx for normal grade and BA4560Rxxx, BA4564RFV, BA4564WFV for high-reliability grade integrate two or four high voltage gain Op-Amps on a single chip. Especially, this series is suitable for any audio applications due to low noise and low distortion characteristics and they are usable for other many applications of wide operating supply voltage range.BA4560Rxxx, BA4564RFV, BA4564WFV are high-reliability products with extended operating temperature range.

Features

- High Voltage Gain, Low Noise, Low Distortion
- Wide Operating Supply Voltage Range
- Wide Operating Temperature Range

 Packages
 W(Typ) x D(Typ) x H(Max)

 SOP8
 5.00mm x 6.20mm x 1.71mm

 SOP-J8
 4.90mm x 6.00mm x 1.65mm

 TSSOP-B8
 3.00mm x 6.40mm x 1.20mm

 MSOP8
 2.90mm x 4.00mm x 0.90mm

 SOP14
 8.70mm x 6.20mm x 1.71mm

 SSOP-B14
 5.00mm x 6.40mm x 1.35mm

Key Specification

- Operating Supply Voltage
- (Split Supply):±4V to ±15V
 Temperature Range: BA4560xxx
 -40°C to +85°C BA4560Rxxx,BA4564RFV,BA4564WFV
 -40°C to +105°C
 Slew Rate:
 4V/µs(Typ)
- Total Harmonic Distortion: 0.003%(Typ)
- Input Referred Noise Voltage: 8 nV/√Hz (Typ)
 Offset Voltage:
 - Offset Voltage: BA4564WFV 2.5mV(Max)

Selection Guide Maximum Operation Temperature +85°C Slew Rate BA4560F Dual 4V/µs Normal BA4560FJ BA4560FV BA4560FVT BA4560FVM +105°C Slew Rate **BA4560RF** BA4560RFJ High Reliability Dual 4V/µs BA4560RFV BA4560RFVT BA4560RFVM BA4564RFV Quad 4V/µs BA4564WFV Simplified Schematic VCC 🗗 VOUT $\sim -\Box$ +IN 🗗 VEE Figure 1. Simplified Schematic

OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

Pin Configuration

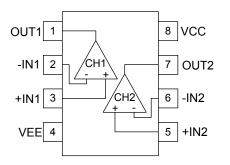
 BA4560F, BA4560RF
 : SOP8

 BA4560FJ, BA4560RFJ
 : SOP-J8

 BA4560FV, BA4560RFV
 : SSOP-B8

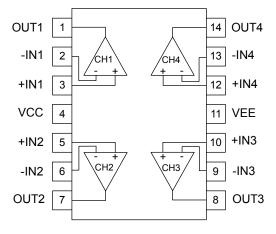
 BA4560FVT, BA4560RFVT
 : TSSOP-B8

 BA4560FVM, BA4560RFVM
 : MSOP8



Pin No.	Pin Name						
1	OUT1						
2	-IN1						
3	+IN1						
4	VEE						
5	+IN2						
6	-IN2						
7	OUT2						
8	VCC						

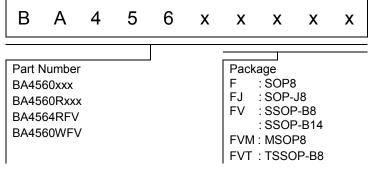
BA4564RFV, BA4564WFV : SSOP-B14



-					
Pin Name					
OUT1					
-IN1					
+IN1					
VCC					
+IN2					
-IN2					
OUT2					
OUT3					
-IN3					
+IN3					
VEE					
+IN4					
-IN4					
OUT4					

Package												
SOP8	SOP-J8	SSOP-B8	TSSOP-B8	MSOP8	SSOP-B14							
BA4560F BA4560RF	BA4560FJ BA4560RFJ	BA4560FV BA4560RFV	BA4560FVT BA4560RFVT	BA4560FVM BA4560RFVM	BA4564RFV BA4564WFV							

Ordering Information



x x

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Packaging and forming specification E2: Embossed tape and reel (SOP8/SSOP-B8/TSSOP-B8/SOP-J8 SSOP-B14) TR: Embossed tape and reel

(MSOP8)

Line-up

Operating Temperature Range	Operating Supply Voltage (Split Supply)	Supply Current (Typ)	Offset Voltage (Max)	Pac	Package Order Part Nu		
				SOP8	Reel of 2500	BA4560F-E2	
				SOP-J8	Reel of 2500	BA4560FJ-E2	
-40°C to +85°C 4m/	4mA		SSOP-B8	Reel of 2500	BA4560FV-E2		
			6mV	TSSOP-B8	Reel of 2500	BA4560FVT-E2	
				MSOP8	Reel of 3000	BA4560FVM-TR	
				SOP8	Reel of 2500	BA4560RF-E2	
	±4.0V to ±15.0V			SOP-J8	Reel of 2500	BA4560RFJ-E2	
		3mA		SSOP-B8	Reel of 2500	BA4560RFV-E2	
-40°C to +105°C				TSSOP-B8	Reel of 3000	BA4560RFVT-E2	
				MSOP8	Reel of 3000	BA4560RFVM-TR	
		6m4		SSOP-B14	Reel of 2500	BA4564RFV-E2	
		6mA	2.5mV	SSOP-B14	Reel of 2500	BA4564WFV-E2	

Absolute Maximum Ratings (T_A=25°C)

Deremeter	-). was host		Ratings							
Parameter		Symbol	BA4560xxx	BA4560Rxxx	BA4564RFV	Unit					
Supply Voltage	V	CC-VEE		+36							
		SOP8	0.55 ^(Note1,6)	0.69 ^(Note1,6)	-	-					
Power Dissipation	P _D	SOP-J8	0.54 ^(Note2,6)	0.67 ^(Note2,6)	-	-					
		SSOP-B8	0.50 ^(Note3,6)	0.62 ^(Note3,6)	-	-					
		TSSOP-B8	0.50 ^(Note3,6)	0.62 ^(Note3,6)	-	-	W				
		MSOP8 0.47 ^(Note4,6) 0.58 ^(Note4,6)									
		SSOP-B14	-	-	0.87 ^(Note5,6)	0.87 ^(Note5,6)					
Differential Input Voltage ^(Note 7)		V _{ID}	VCC-VEE			V					
Input Common-mode Voltage Range		VICM	VEE to VCC	(VE	E+36	V					
Input Current ^(Note 8)		lı –		-	10		mA				
Operating Supply Voltage Range		V _{opr}		+8 to +30	(±4 to ±15)		V				
Operating Temperature Range		T _{opr}	-40 to +85		-40 to +105		°C				
Storage Temperature Range		T _{stg}	-55 to +125			°C					
Maximum Junction Temperature	T _{JMAX}		+125	+150							

Note: Absolute maximum rating item indicates the condition which must not be exceeded.

Application of voltage in excess of absolute maximum rating or use out absolute maximum rated temperature environment may cause

deterioration of characteristics.

(Note 1) To use at temperature above $T_{\text{A}}{=}25^{\circ}\text{C}~\text{reduce}~5.5\text{mW}.$

(Note 2) To use at temperature above $T_A = 25^{\circ}C$ reduce 5.4mW.

(Note 3) To use at temperature above $T_A=25^{\circ}C$ reduce 5.0mW. (Note 4) To use at temperature above $T_A=25^{\circ}C$ reduce 4.7mW.

(Note 4) To use at temperature above $T_A = 25^{\circ}$ C reduce 4.711W. (Note 5) To use at temperature above $T_A = 25^{\circ}$ C reduce 7.0mW.

(Note 6) Mounted on a FR4 glass epoxy PCB(70mm×70mm×1.6mm).

(Note 6) Mounted on a FR4 glass epoxy PCB(/Umm×/Umm×1.6mm).

(Note 7) The voltage difference between inverting input and non-inverting input is the differential input voltage.

Then input terminal voltage is set to more than VEE.

(Note 8) An excessive input current will flow when input voltages of less than VEE-0.6V are applied.

The input current can be set to less than the rated current by adding a limiting resistor. Caution: Operating the IC over the absolute maximum ratings may damage the IC. In addition, it is impossible to predict all destructive situations such as short-circuit modes, open circuit modes, etc. Therefore, it is important to consider circuit protection measures, like adding a fuse, in case the IC is operated in a special mode exceeding the absolute maximum ratings.

Electrical Characteristics

OBA4560xxx (Unless otherwise specified VCC=+15V, VEE=-15V)

Deremeter	Cumphel	Temperature		Limits		Linit	Condition
Parameter	Symbol	Range	Min	Тур	Max	Unit	Condition
Input Offset Voltage (Note 9)	V _{IO}	25°C	-	0.5	6	mV	VOUT=0V
Input Offset Current (Note 9)	lio	25°C	-	5	200	nA	VOUT=0V
Input Bias Current (Note 10)	I _B	25°C	-	50	500	nA	VOUT=0V
Supply Current	I _{CC}	25°C	-	4	7.5	mA	R _L =∞, All Op-Amps, VIN+=0V
	V	25°C	±12	±14	-	v	R _L ≥ 10kΩ
Maximum Output Voltage	V _{OM}	25°C	±10	±13	-	V	R _L ≥ 2kΩ
Large Signal Voltage Gain	A _V	25°C	86	100	-	dB	$\begin{array}{l} R_{L} \geq 2k\Omega, \ VOUT=\pm 10V \\ V_{ICM}=0V \end{array}$
Input Common-mode Voltage Range	VICM	25°C	±12	±14	-	V	-
Common-mode Rejection Ratio	CMRR	25°C	70	90	-	dB	V _{ICM} =-12V~+12V
Power Supply Rejection Ratio	PSRR	25°C	76.3	90	-	dB	R _l ≤ 10kΩ
Slew Rate	SR	25°C	-	4	-	V/µs	A_V =0dB, R _L =2k Ω C _L =100pF
Unity Gain Frequency	f⊤	25°C	-	4	-	MHz	R _L =2kΩ
Gain Band Width	GBW	25°C	-	10	-	MHz	f=10kHz
Total Harmonic Distortion+Noise	THD+N	25°C	-	0.003	-	%	A_V =20dB, R _L =2k Ω VIN=0.05Vrms, f=1kHz
	\ <i>.</i>		-	8	-	nV/√Hz	R _S =100Ω, V _I =0V f=1kHz
Input Referred Noise Voltage	V _N	25°C	-	-	2.2	µVrms	R _S =2.2Ω, RIAA BW=10kHz to 30kHz

(Note 9) Absolute value

(Note 10) Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

OBA4560Rxxx (Unless otherwise specified VCC=+15V, VEE=-15V, Full range -40°C to +105°C)

Parameter	Symbol	Temperature		Limits		Unit	Condition
Falameter	Symbol	Range	Min	Тур	Max	Unit	Condition
Input Offset Voltage (Note 11)	VIO	25°C	-	0.5	6	mV	VOUT=0V
input Onset Voltage	•10	Full range	-	-	7	IIIV	001-00
Input Offset Current (Note 11)	I _{IO}	25°C	-	5	200	nA	VOUT=0V
	10	Full range	-	-	200	10.1	001-00
Input Bias Current (Note 12)	I _B	25°C	-	50	500	nA	VOUT=0V
	·B	Full range	-	-	800		
Supply Current	I _{CC}	25°C	-	3	7	mA	R _L =∞, All Op-Amps
	100	Full range	-	-	7.5		VIN+=0V
Maximum Output Voltage	V _{OM}	25°C	±12	±14	-	v	R _L ≥ 2kΩ
maximum culput reliage	• OW	Full range	±10	±11.5	-		I _O =25mA
Large Signal Voltage Gain	Av	25°C	86	100	-	dB	$R_{L} \ge 2k\Omega$, VOUT=±10V
		Full range	83	-	-	40	V _{ICM} =0V
Input Common-mode Voltage Range	VICM	25°C	±12	±14	-	v	_
		Full range	±12	-	-	v	
Common-mode Rejection Ratio	CMRR	25°C	70	90	-	dB	V _{ICM} =-12V~+12V
Power Supply Rejection Ratio	PSRR	25°C	76.5	90	-	dB	Ri≦ 10kΩ
Channel Separation	CS	25°C	-	105	-	dB	R1=100Ω,f=1kHz
Slew Rate	SR	25°C	-	4	-	V/µs	$A_V=0$ dB, R _L =2k Ω C _L =100pF
Unity Gain Frequency	f⊤	25°C	-	4	-	MHz	R _L =2kΩ
Total Harmonic Distortion+Noise	THD+N	25°C	-	0.003	-	%	A _V =20dB, R _L =2kΩ VIN=0.05Vrms, f=1kHz
		25°C	-	8	-	nV/√Hz	R _S =100Ω, V _I =0V f=1kHz
Input Referred Noise Voltage	V _N	20 C	-	1.0	-	µVrms	DIN-AUDIO

(Note 11) Absolute value

(Note 12) Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

OBA4564RFV (Unless otherwise specified VCC=+15V, VEE=-15V, Full range -40°C to +105°C)

Parameter		Temperature		Limits	<u> </u>	Unit	Condition
Parameter	Symbol	Range	Min	Тур	Max	Unit	Condition
Input Offset Voltage (Note 13)	V _{IO}	25°C	-	0.5	6	mV	VOUT=0V
input Onset voltage	VIO	Full range	-	-	7	IIIV	001-00
Input Offset Current (Note 13)	I _{IO}	25°C	-	5	200	nA	VOUT=0V
	10	Full range	-	-	200	11/ \	
Input Bias Current (Note 14)	I _B	25°C	-	50	500	nA	VOUT=0V
	.0	Full range	-	-	800		
Supply Current	I _{CC}	25°C	-	6	14	mA	R _L =∞, All Op-Amps
	100	Full range	-	-	15		VIN+=0V
Maximum Output Voltage	V _{OM}	25°C	±12	±14	-	V	R _L ≥ 2kΩ
	0	Full range	±10	±11.5	-		I ₀ =25mA
Large Signal Voltage Gain	Av	25°C	86	100	-	dB	$R_{L} \ge 2k\Omega$, VOUT=±10V
		Full range	83	-	-		V _{ICM} =0V
Input Common-mode Voltage Range	VICM	25°C	±12	±14	-	V	-
		Full range	±12	-	-		
Common-mode Rejection Ratio	CMRR	25°C	70	90	-	dB	V _{ICM} =-12V~+12V
Power Supply Rejection Ratio	PSRR	25°C	76.5	90	-	dB	Ri≤ 10kΩ
Channel Separation	CS	25°C	-	105	-	dB	R1=100Ω, f=1kHz
Slew Rate	SR	25°C	-	4	-	V/µs	A_V =0dB, R _L =2k Ω C _L =100pF
Unity Gain Frequency	f⊤	25°C	-	4	-	MHz	$R_L=2k\Omega$
Total Harmonic Distortion+Noise	THD+N	25°C	-	0.003	-	%	A _V =20dB, R _L =2kΩ VIN=0.05Vrms, f=1kHz
		25°C	-	8	-	nV/√Hz	R _s =100Ω, V _I =0V f=1kHz
Input Referred Noise Voltage	V _N	25 C	-	1.0	-	µVrms	DIN-AUDIO

(Note 13) Absolute value

(Note 14) Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

OBA4564WFV (Unless otherwise specified VCC=+15V, VEE=-15V, Full range -40°C to +105°C)

		T		Limits			
Parameter	Symbol	Temperature Range	BA	\4564WI	=V	Unit	Condition
			Min	Тур	Max		
Input Offset Voltage (Note 15)	V _{IO}	25°C	-	0.5	2.5	mV	VOUT=0V
input onset voltage	•10	Full range	-	-	4	IIIV	001-00
Input Offset Current (Note 15)	I _{IO}	25°C	-	5	200	nA	VOUT=0V
	10	Full range	-	-	200	10.	001-00
Input Bias Current (Note 16)	IB	25°C	-	50	300	nA	VOUT=0V
	IB	Full range	-	-	500		001-00
Supply Current	Icc	25°C	-	6	11	mA	R _L =∞, All Op-Amps
	ICC	Full range	-	-	13	шл	VIN+=0V
Maximum Output Voltage	V _{OM}	25°C	±12	±14	-	v	R _L ≥ 2kΩ
Maximum Output Voltage	V OM	Full range	±10	±11.5	-	v	I ₀ =25mA
Large Signal Voltage Gain	Av	25°C	86	100	-	dB	$R_L \ge 2k\Omega$, VOUT=±10V
	Αv	Full range	83	-	-	UD	V _{ICM} =0V
Input Common-mode Voltage Range	V _{ICM}	25°C	±12	±14	-	v	_
input common-mode voltage Range		Full range	±12	-	-	v	-
Common-mode Rejection Ratio	CMRR	25°C	70	90	-	dB	V _{ICM} =-12V~+12V
Power Supply Rejection Ratio	PSRR	25°C	76.5	90	-	dB	R _I ≤ 10kΩ
Channel Separation	CS	25°C	-	105	-	dB	R1=100Ω, f=1kHz
Slew Rate	SR	25°C	-	4	-	V/µs	A_V =0dB, R _L =2k Ω C _L =100pF
Unity Gain Frequency	f⊤	25°C	-	4	-	MHz	$R_L=2k\Omega$
Total Harmonic Distortion+Noise	THD+N	25°C	-	0.003	-	%	A _V =20dB, R _L =2kΩ VIN=0.05Vrms, f=1kHz
	N/	25°C	-	8	-	nV/√Hz	R _s =100Ω, V _I =0V f=1kHz
Input Referred Noise Voltage	V _N	200	-	1.0	-	µVrms	DIN-AUDIO

(Note 15) Absolute value

(Note 16) Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

Description of electrical characteristics

Described here are the terms of electric characteristics used in this datasheet. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacture's document or general document.

1. Absolute maximum ratings

Absolute maximum rating item indicates the condition which must not be exceeded. Application of voltage in excess of absolute maximum rated temperature environment may cause deterioration of characteristics.

1.1 Power supply voltage (VCC-VEE)

Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.

- 1.2 Differential input voltage (V_{ID}) Indicates the maximum voltage that can be applied between non-inverting terminal and inverting terminal without deterioration and destruction of characteristics of IC.
- 1.3 Input common-mode voltage range (V_{ICM})

Indicates the maximum voltage that can be applied to non-inverting terminal and inverting terminal without deterioration or destruction of characteristics. Input common-mode voltage range of the maximum ratings not assure normal operation of IC. When normal operation of IC is desired, the input common-mode voltage of characteristics item must be followed.

1.4 Power dissipation (P_D)

Indicates the power that can be consumed by specified mounted board at the ambient temperature $25^{\circ}C$ (normal temperature). As for package product, P_D is determined by the temperature that can be permitted by IC chip in the package (maximum junction temperature) and thermal resistance of the package.

2. Electrical characteristics item

- 2.1 Input offset voltage (V_{IO})
 - Indicates the voltage difference between non-inverting terminal and inverting terminal. It can be translated into the input voltage difference required for setting the output voltage at 0 V.
- 2.2 Input offset current (I_{IO}) Indicates the difference of input bias current between non-inverting terminal and inverting terminal.
- 2.3 Input bias current (I_B) Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias current at non-inverting terminal and input bias current at inverting terminal.
- 2.4 Input common-mode voltage range(V_{ICM}) Indicates the input voltage range where IC operates normally.
- 2.5 Large signal voltage gain (A_V) Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting terminal and Inverting terminal. It is normally the amplifying rate (gain) with reference to DC voltage. A_V = (Output voltage fluctuation) / (Input offset fluctuation)
- 2.6 Circuit current (I_{CC}) Indicates the IC current that flows under specified conditions and no-load steady status.
- 2.7 Output saturation voltage (V_{OM}) Signifies the voltage range that can be output under specific output conditions.
- 2.8 Common-mode rejection ratio (CMRR) Indicates the ratio of fluctuation of input offset voltage when in-phase input voltage is changed. It is normally the fluctuation of DC. CMRR = (Change of Input common-mode voltage) / (Input offset fluctuation)
- 2.9 Power supply rejection ratio (PSRR)
 Indicates the ratio of fluctuation of input offset voltage when supply voltage is changed. It is normally the fluctuation of DC.

 PSRR = (Change of power supply voltage) / (Input offset fluctuation)
- 2.10 Unity gain frequency (ft) Indicates a frequency where the voltage gain of operational amplifier is 1.

2.11 Slew Rate (SR)

SR is a parameter that shows movement speed of operational amplifier. It indicates rate of variable output voltage as unit time.

2.12 Gain Band Width (GBW)

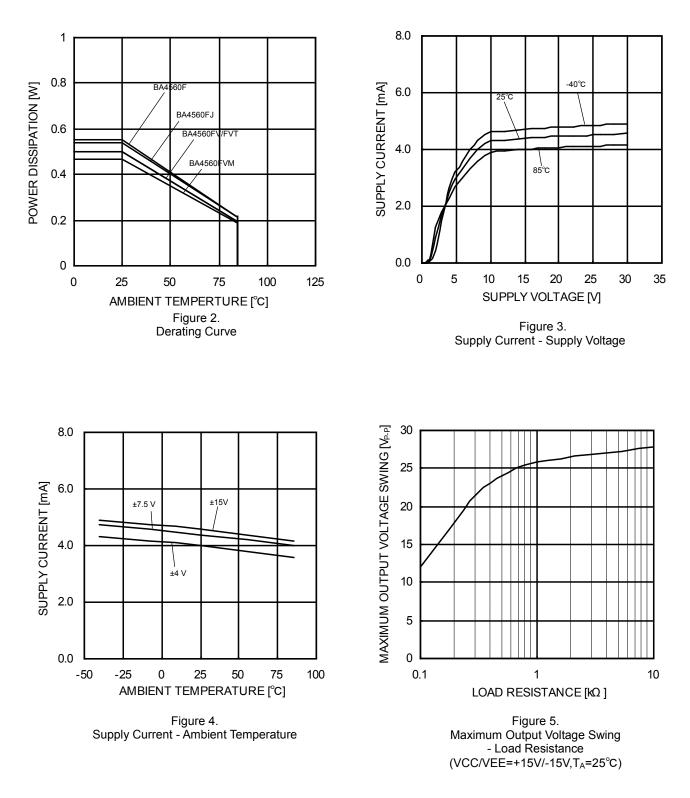
Indicates to multiply by the frequency and the gain where the voltage gain decreases 6dB/octave.

- 2.13 Total harmonic distortion + Noise (THD+N) Indicates the fluctuation of input offset voltage or that of output voltage with reference to the change of output voltage of driven channel.
- 2.14 Input referred noise voltage (V_N)

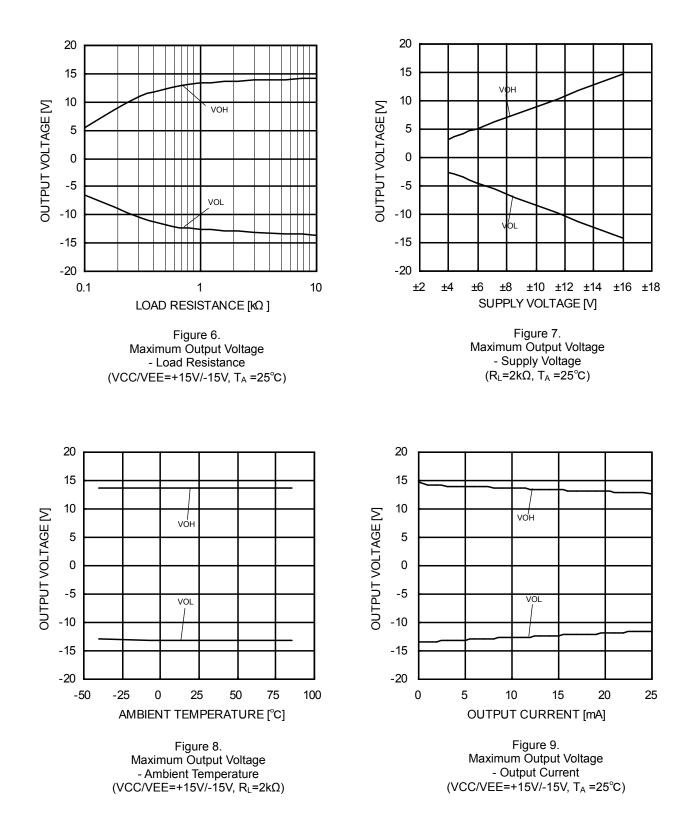
Indicates a noise voltage generated inside the operational amplifier equivalent by ideal voltage source connected in series with input terminal.

Typical Performance Curves

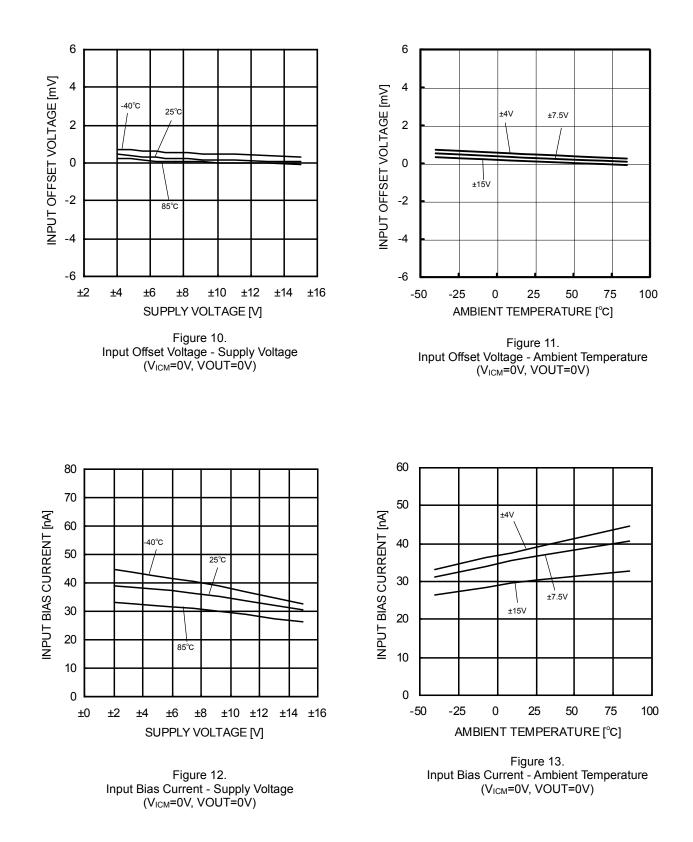
OBA4560xxx



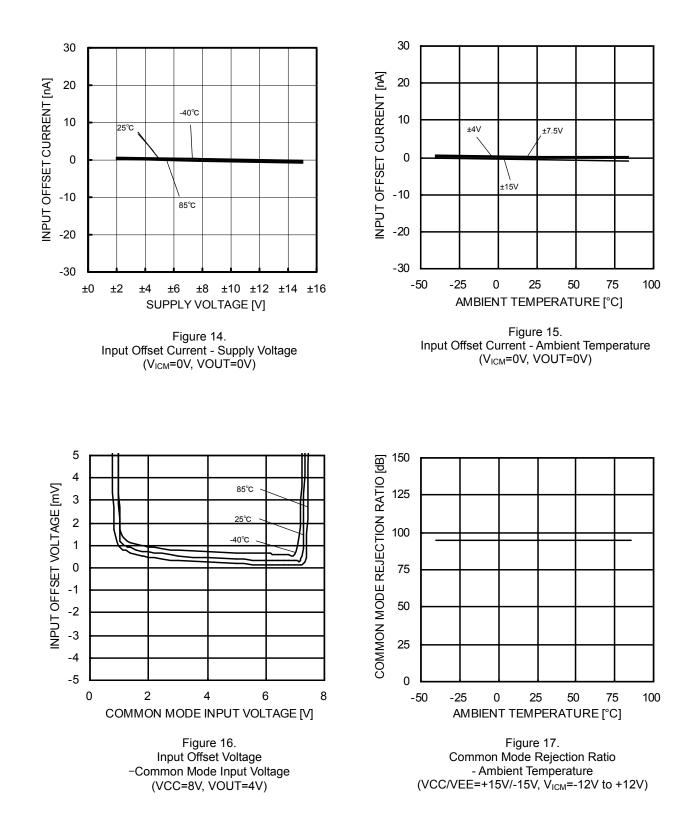
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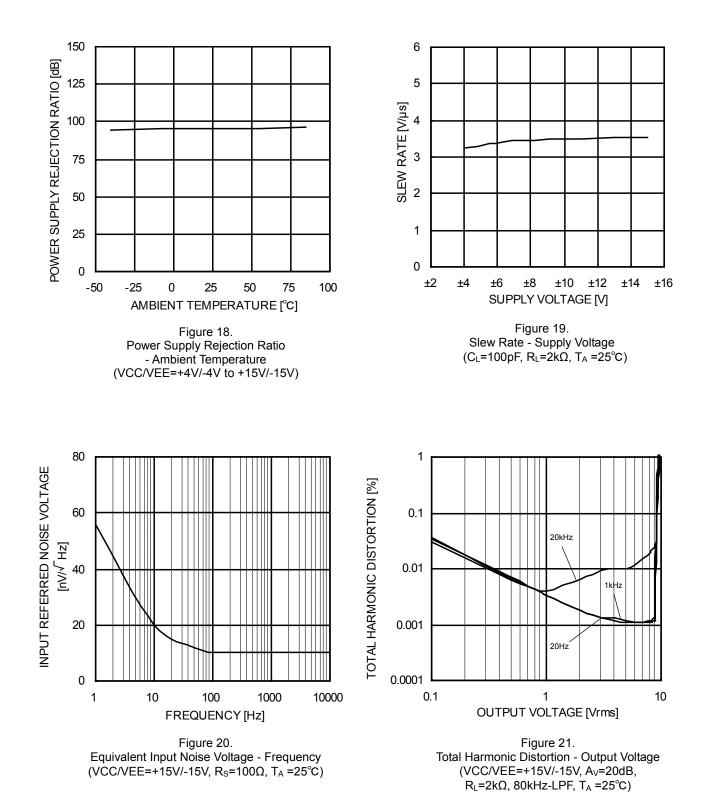
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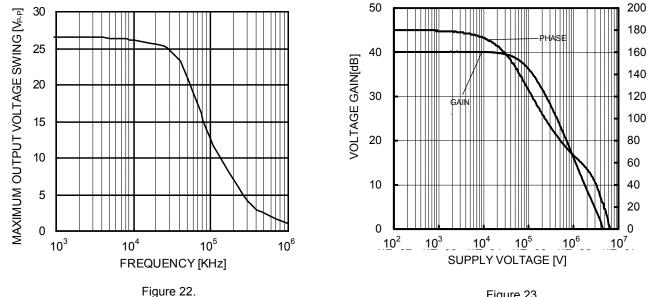
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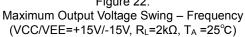


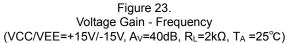
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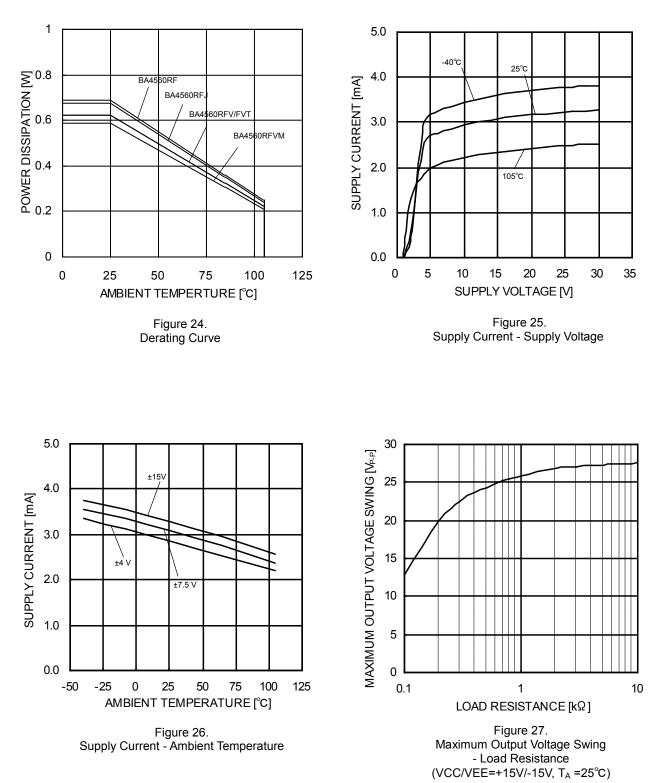
OBA4560xxx



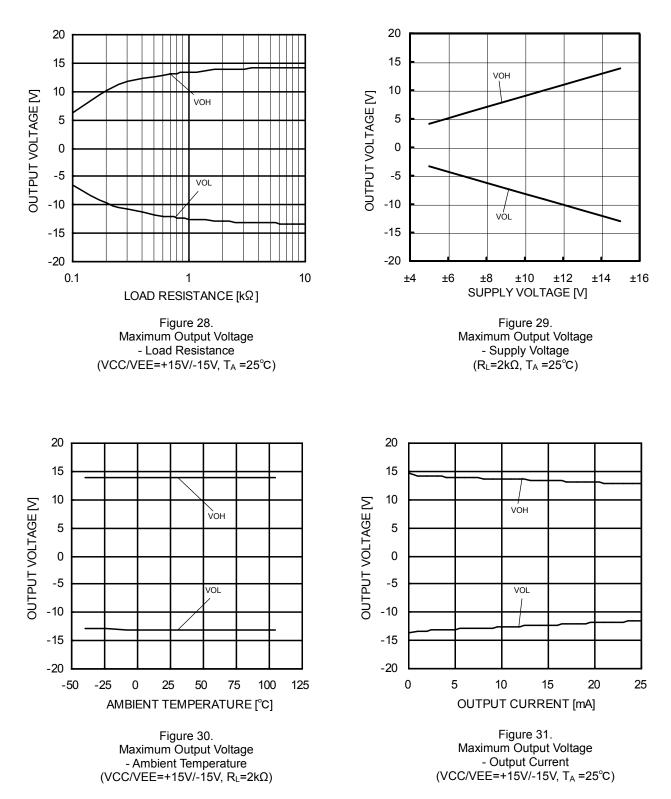




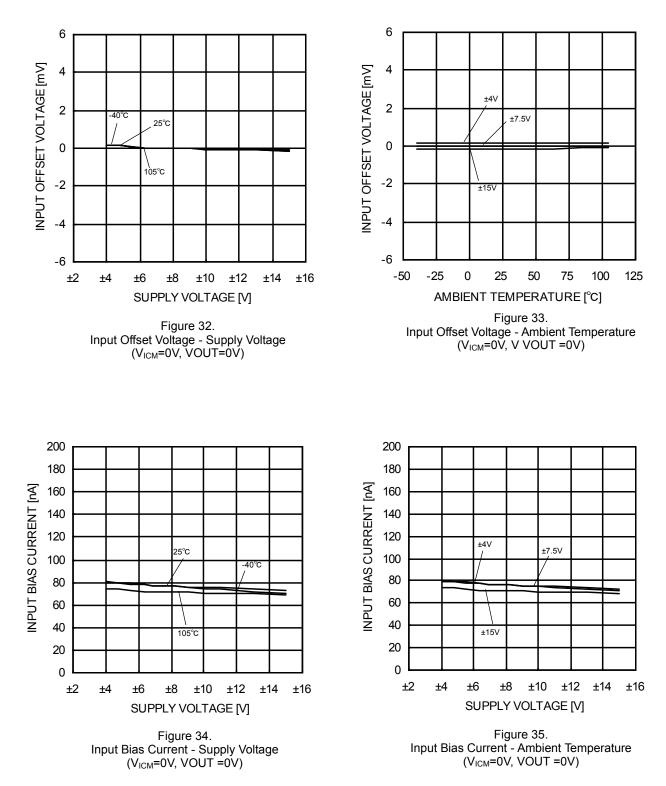
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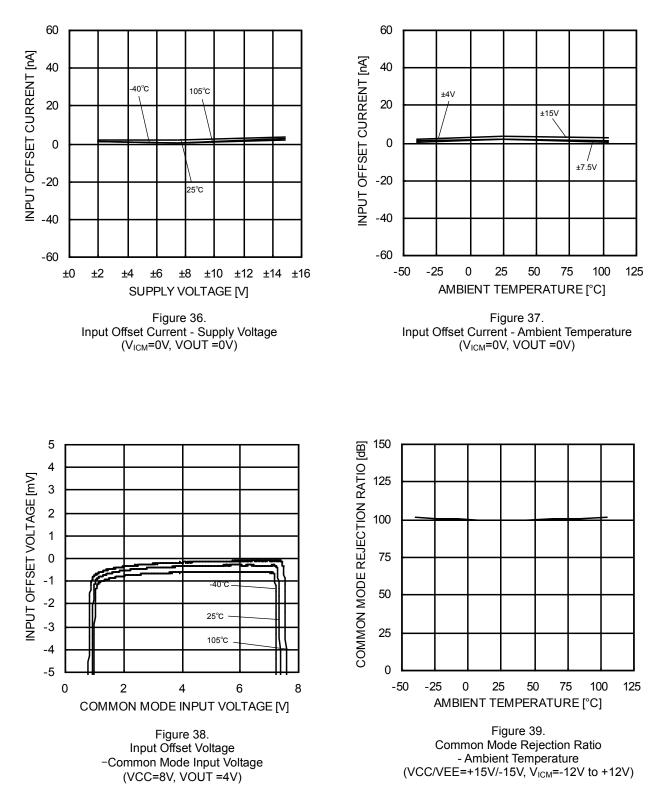
 $(\ensuremath{^*})\ensuremath{\mathsf{The}}$ above data is measurement value of typical sample, it is not guaranteed.



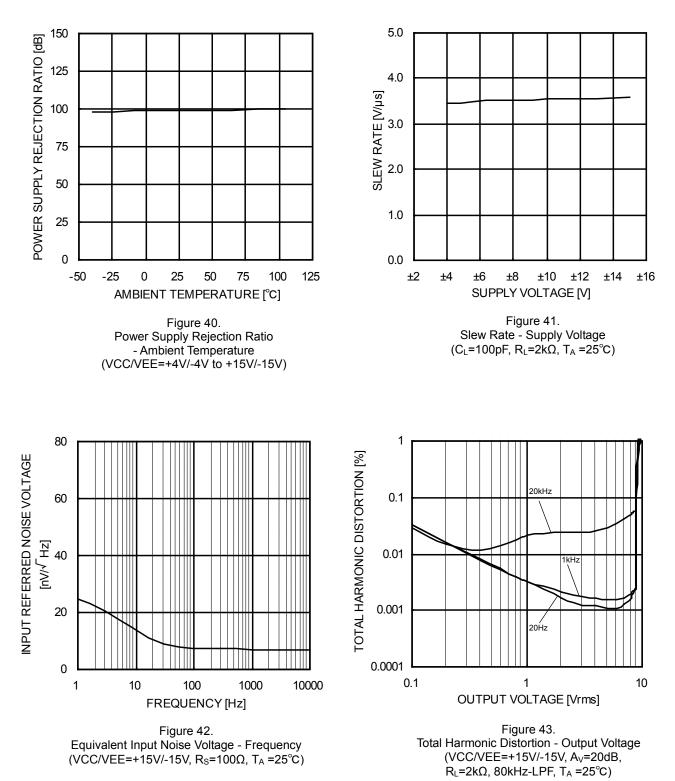
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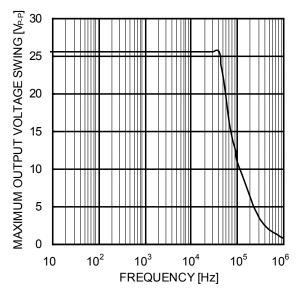
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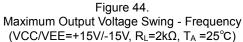


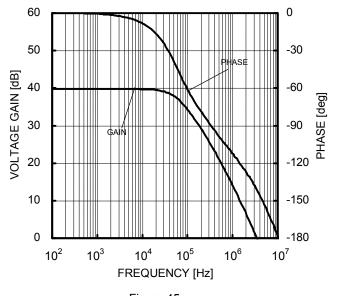
(*)The above data is measurement value of typical sample, it is not guaranteed.

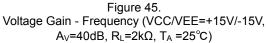


(*)The above data is measurement value of typical sample, it is not guaranteed.

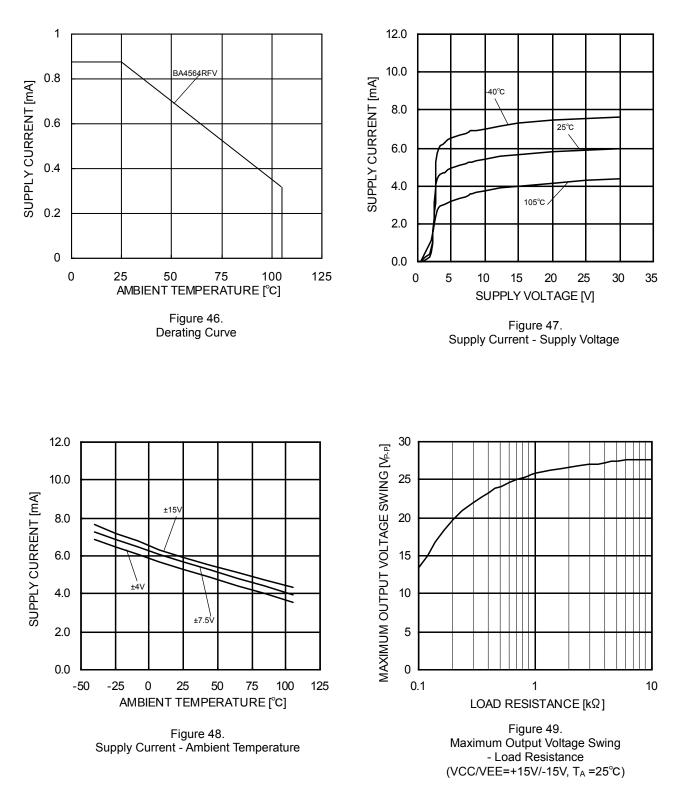




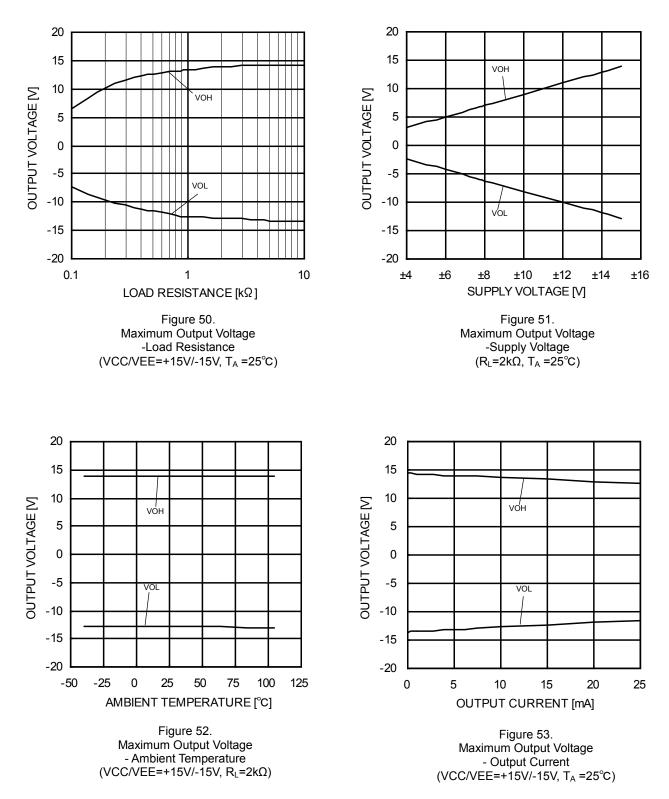




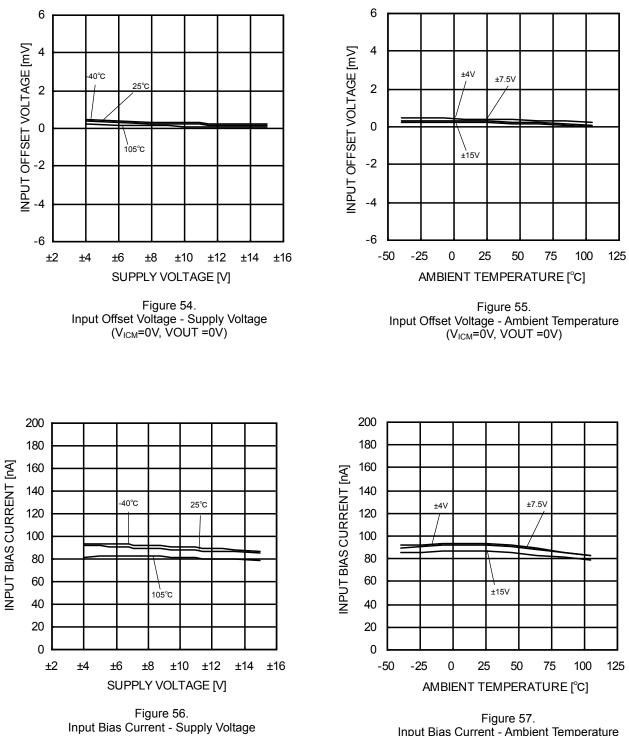
(*)The above data is measurement value of typical sample, it is not guaranteed.



 $(\ensuremath{^*})\ensuremath{\mathsf{The}}$ above data is measurement value of typical sample, it is not guaranteed.



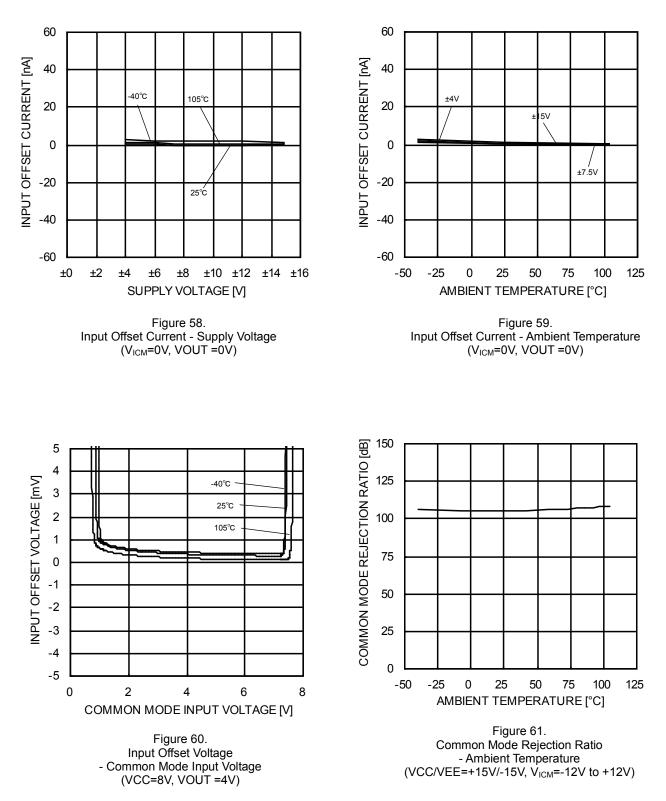
(*)The above data is measurement value of typical sample, it is not guaranteed.



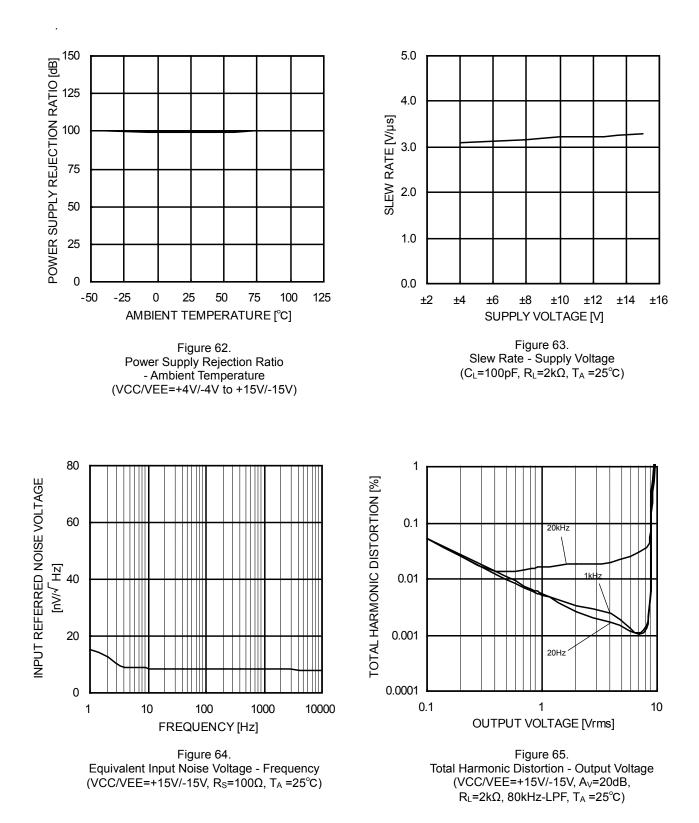
(V_{ICM}=0V, VOUT =0V)

Input Bias Current - Ambient Temperature (V_{ICM}=0V, VOUT =0V)

(*)The above data is measurement value of typical sample, it is not guaranteed.



(*)The above data is measurement value of typical sample, it is not guaranteed.



(*)The above data is measurement value of typical sample, it is not guaranteed.

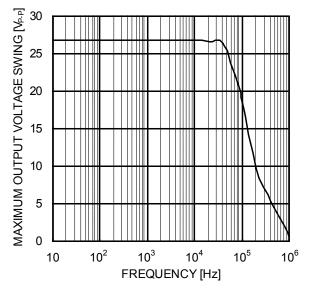


Figure 66. Maximum Output Voltage Swing – Frequency (VCC/VEE=+15V/-15V, $R_L=2k\Omega$, $T_A=25^{\circ}C$)

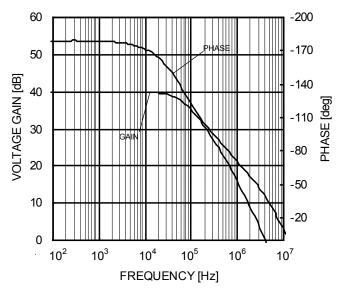
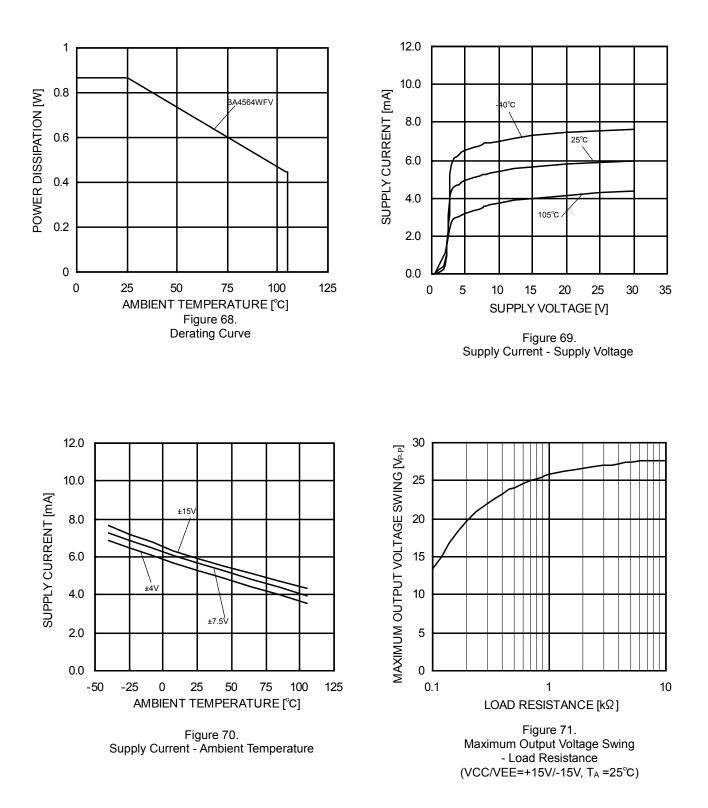
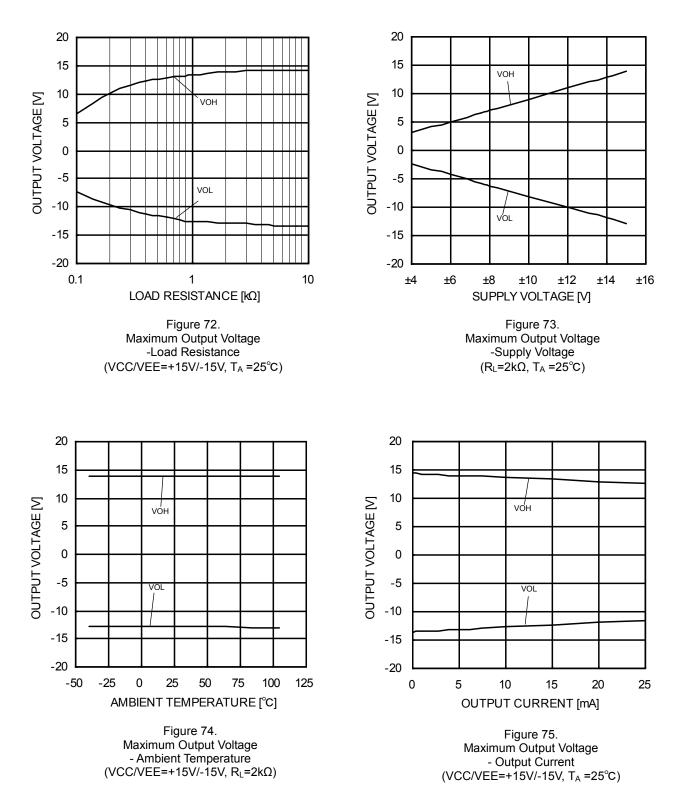


Figure 67. Voltage Gain - Frequency (VCC/VEE=+15V/-15V, A_V =40dB, R_L =2k Ω , T_A =25°C)

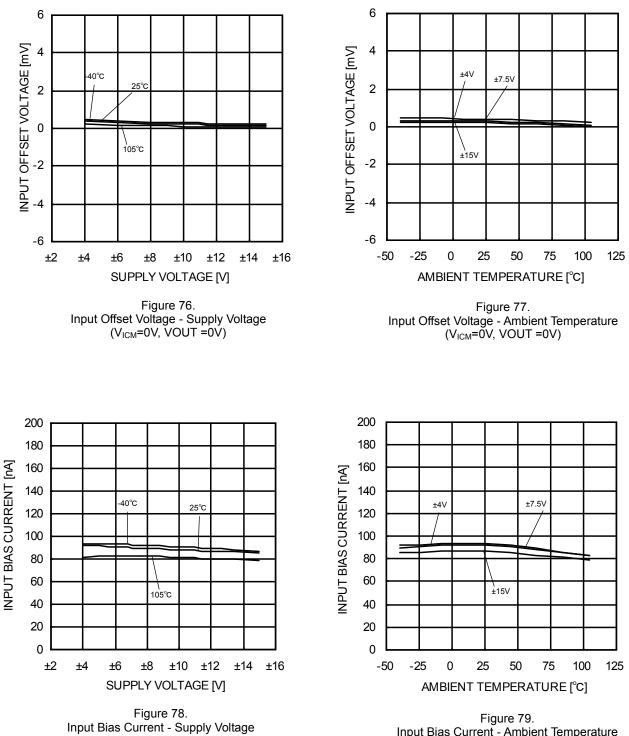
(*)The above data is measurement value of typical sample, it is not guaranteed.



(*)The above data is measurement value of typical sample, it is not guaranteed.



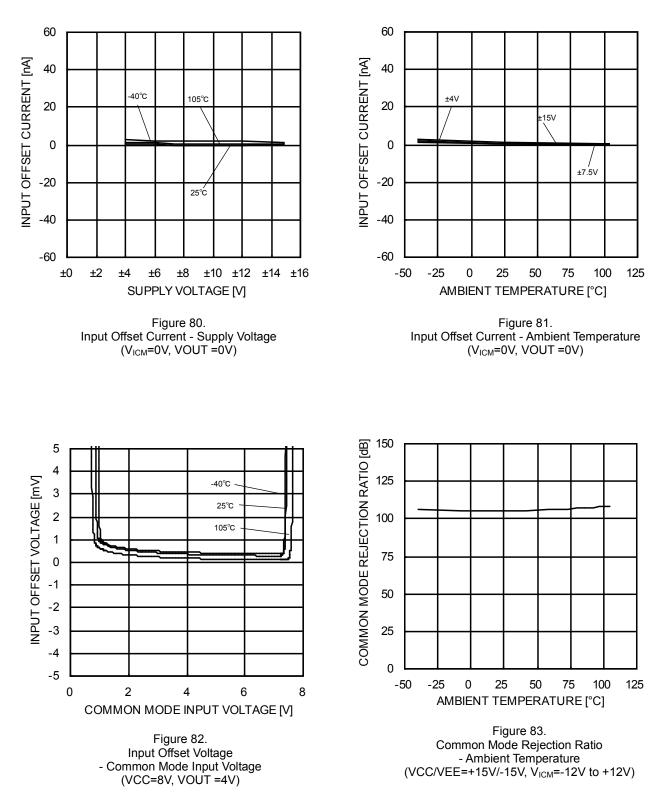
(*)The above data is measurement value of typical sample, it is not guaranteed.



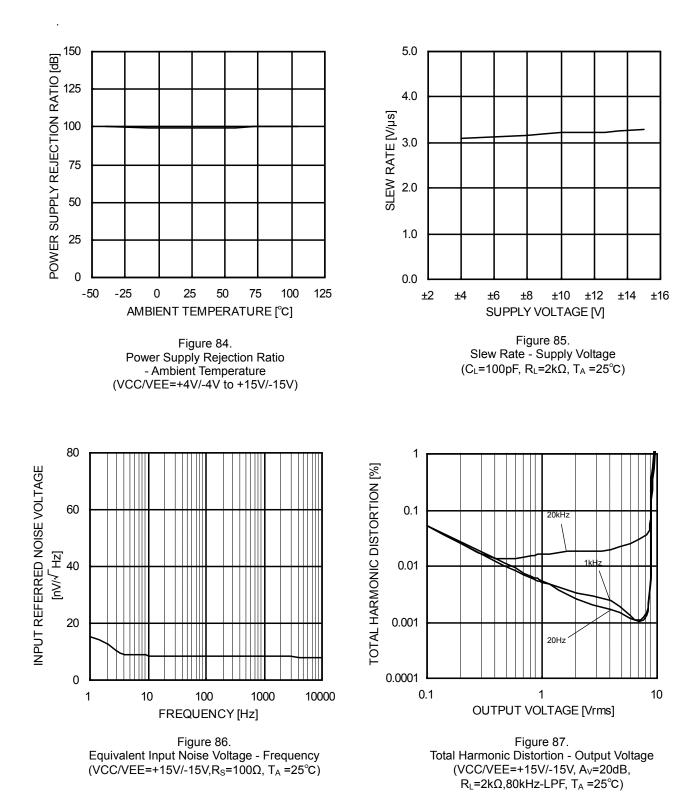
(V_{ICM}=0V, VOUT=0V)

Input Bias Current - Ambient Temperature $(V_{ICM}=0V, VOUT=0V)$

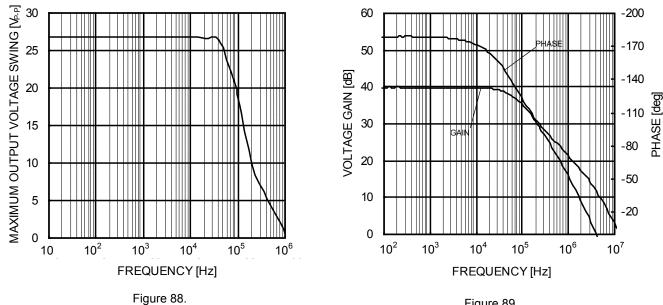
(*)The above data is measurement value of typical sample, it is not guaranteed.



(*)The above data is measurement value of typical sample, it is not guaranteed.



 $(\ensuremath{^*})\ensuremath{\mathsf{The}}$ above data is measurement value of typical sample, it is not guaranteed.



Maximum Output Voltage Swing – Frequency (VCC/VEE=+15V/-15V, $R_L=2k\Omega$, $T_A=25^{\circ}C$)

Figure 89. Voltage Gain - Frequency (VCC/VEE=+15V/-15V, Av=40dB, R_L =2 $k\Omega$, T_A =25°C)

(*)The above data is measurement value of typical sample, it is not guaranteed.

Application Information Test Circuit1 NULL method

		1					VCC, V	/ΕΕ, Ε _κ , '	V _{ICM} Unit: ۱
Parameter	V _F	S1	S2	S3	VCC	VEE	Eκ	V _{ICM}	Calculation
Input Offset Voltage	V _{F1}	ON	ON	OFF	15	-15	0	0	1
Input Offset Current	V _{F2}	OFF	OFF	OFF	15	-15	0	0	2
Janua Ding Current	V _{F3}	OFF	ON	055	4-	45	0	0	3
Input Bias Current	V_{F4}	ON	OFF	OFF	15	-15	0	0	
	V _{F5}			0.1	15	-15	0	0	4
Large Signal Voltage Gain	V _{F6}	ON	ON	ON	15	-15	0	0	4
Common-mode Rejection Ratio	V _{F7}				3	-27	-12	0	F
(Input common-mode Voltage Range)	V _{F8}	ON	ON	OFF	27	-3	12	0	5
Power Supply	V_{F9}			0.55	4	-4	0	0	6
Rejection Ratio	V _{F10}	ON	ON	OFF	15	-15	0	0	6

-Calculation-

1. Input Offset Voltage (V_{IO})

$$V_{IO} = \frac{|V_{F1}|}{1 + R_F/R_S} [V]$$

2. Input Offset Current (I_{IO})

$$I_{IO} = \frac{|V_{F2}-V_{F1}|}{|R_{I} \times (1+R_{F}/R_{S})|}$$
[A]

3. Input Bias Current (I_B)

$$I_{B} = \frac{|V_{F4} - V_{F3}|}{2 \times R_{I} \times (1 + R_{F}/R_{S})}$$
 [A]

4. Large Signal Voltage Gain (A_V)

$$A_{V} = 20Log \quad \frac{\Delta E_{K} \times (1+R_{F}/R_{S})}{|V_{F5}-V_{F6}|} \quad [dB]$$

- 5. Common-mode Rejection Ration (CMRR) $CMRR = 20Log \frac{\Delta V_{ICM} \times (1+R_F/R_S)}{|V_{F8}-V_{F7}|} [dB]$
- 6. Power supply rejection ratio (PSRR) PSRR=20Log $\frac{\Delta V_{CC} \times (1 + R_F/R_S)}{|V_{F10} - V_{F9}|}$ [dB]

Test Circuit 2 Switch Condition

SW No.	SW1	SW2	SW3	SW4	SW5	SW6	SW7	SW8	SW9	SW10	SW11	SW12	SW13	SW14
Supply Current	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
High Level Output Voltage	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF
Low Level Output Voltage	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF
Slew Rate	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	OFF	OFF
Unity Gain Frequency	OFF	ON	OFF	OFF	ON	ON	OFF	OFF	ON	ON	ON	OFF	OFF	OFF
Total Harmonic Distortion	ON	OFF	OFF	OFF	ON	OFF	ON	OFF	ON	ON	ON	OFF	OFF	OFF
Input Referred Noise Voltage	ON	OFF	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF

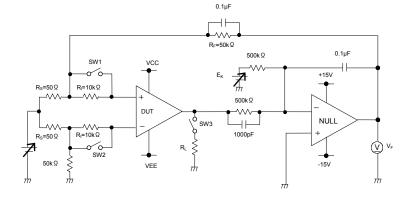
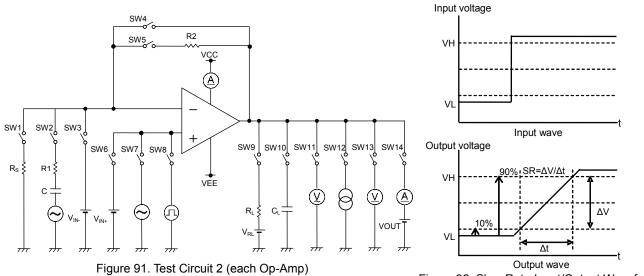


Figure 90. Test Circuit1 (one channel only)





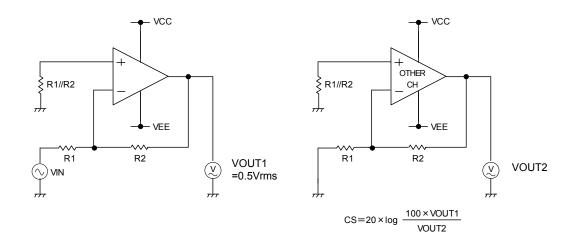


Figure 93. Test Circuit 3(Channel Separation) (VCC=+15V, VEE=-15V, R1=1k Ω , R2=100k Ω)

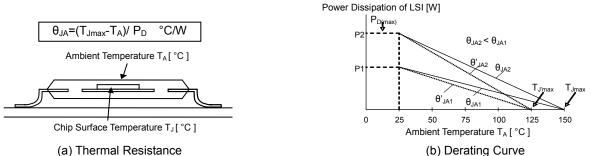
Power Dissipation

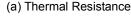
Power dissipation(total loss) indicates the power that can be consumed by IC at T_A =25°C(normal temperature). IC is heated when it consumed power, and the temperature of IC chip becomes higher than ambient temperature. The temperature that can be accepted by IC chip depends on circuit configuration, manufacturing process, and consumable power is limited. Power dissipation is determined by the temperature allowed in IC chip(maximum junction temperature) and thermal resistance of package(heat dissipation capability). The maximum junction temperature is typically equal to the maximum value in the storage temperature range. Heat generated by consumed power of IC radiates from the mold resin or lead

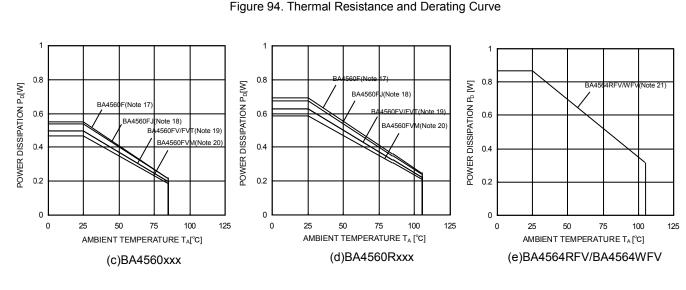
frame of the package. The parameter which indicates this heat dissipation capability(hardness of heat release)is called thermal resistance, represented by the symbol $\theta_{JA}^{\circ}C/W$. The temperature of IC inside the package can be estimated by this thermal resistance. Figure 94.(a) shows the model of thermal resistance of the package. Thermal resistance θ_{JA} , ambient temperature T_A, junction temperature T_{JMAX}, and power dissipation P_D can be calculated by the equation below:

$$\theta_{JA} = (T_{JMAX} - T_A) / P_D$$
 °C/W

Derating curve in Figure 94. (b) indicates power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC with reference to ambient temperature. Power that can be consumed by IC begins to attenuate at certain ambient temperature. This gradient is determined by thermal resistance θ_{JA} . Thermal resistance θ_{JA} depends on chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 95.(c), to, (e) show a derating curve for an example of BA4560xxx, BA4560Rxxx, BA4564RFV, BA4564WFV.







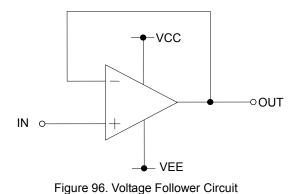
(Note 17)	(Note 18)	(Note 19)	(Note 20)	(Note 21)	Unit		
5.5	5.4	5.0	4.7	7.0	mW/°C		
With the state T offor the the test of the state of the s							

When using the unit above $T_A=25^{\circ}C$, subtract the value above per degree C. Permissible dissipation is the value. Permissible dissipation is the value when FR4 glass epoxy board 70mm ×10mm ×1.6mm (cooper foil area below 3%) is mounted.

Figure 95. Derating Curve

Examples of Circuit

OVoltage Follower



Voltage gain is 0dB.

Using this circuit, the output voltage (OUT) is configured to be equal to the input voltage (IN). This circuit also stabilizes the output voltage (OUT) due to high input impedance and low output impedance. Computation for output voltage (OUT) is shown below. OUT=IN

OInverting Amplifier

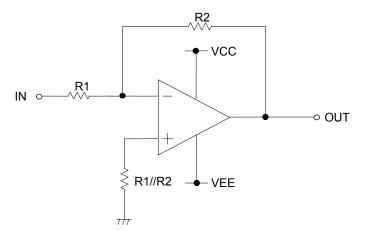
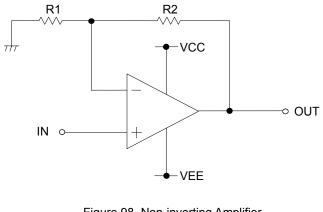
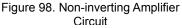


Figure 97. Inverting Amplifier Circuit

ONon-inverting Amplifier





For inverting amplifier, input voltage (IN) is amplified by a voltage gain and depends on the ratio of R1 and R2. The out-of-phase output voltage is shown in the next expression

OUT=-(R2/R1) · IN

This circuit has input impedance equal to R1.

For non-inverting amplifier, input voltage (IN) is amplified by a voltage gain, which depends on the ratio of R1 and R2. The output voltage (OUT) is in-phase with the input voltage (IN) and is shown in the next expression.

OUT=(1 + R2/R1) · IN

Effectively, this circuit has high input impedance since its input side is the same as that of the operational amplifier.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. The absolute maximum rating of the P_D stated in this specification is when the IC is mounted on a 70mm x 70mm x 1.6mm glass epoxy board. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the P_D rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

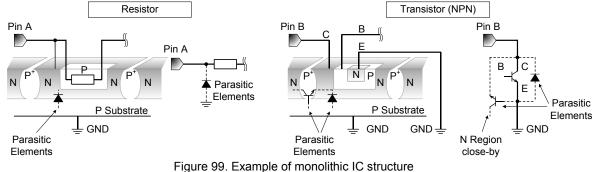
Operational Notes – continued

11. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.



12. Unused Circuits

It is recommended to apply the connection (see Figure 100.) and set the non-inverting input terminal at a potential within the Input Common-mode Voltage Range (VICM) for any unused circuit.

13. Input Voltage

Applying VEE +36V to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, regardless of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.

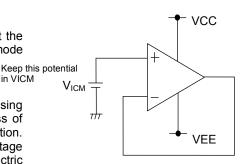


Figure 100. Example of Application Circuit for Unused Op-amp

14. Power Supply(single/dual)

The operational amplifier operates when the voltage supplied is between VCC and VEE. Therefore, the single supply operational amplifier can be used as dual supply operational amplifier as well.

in VICM

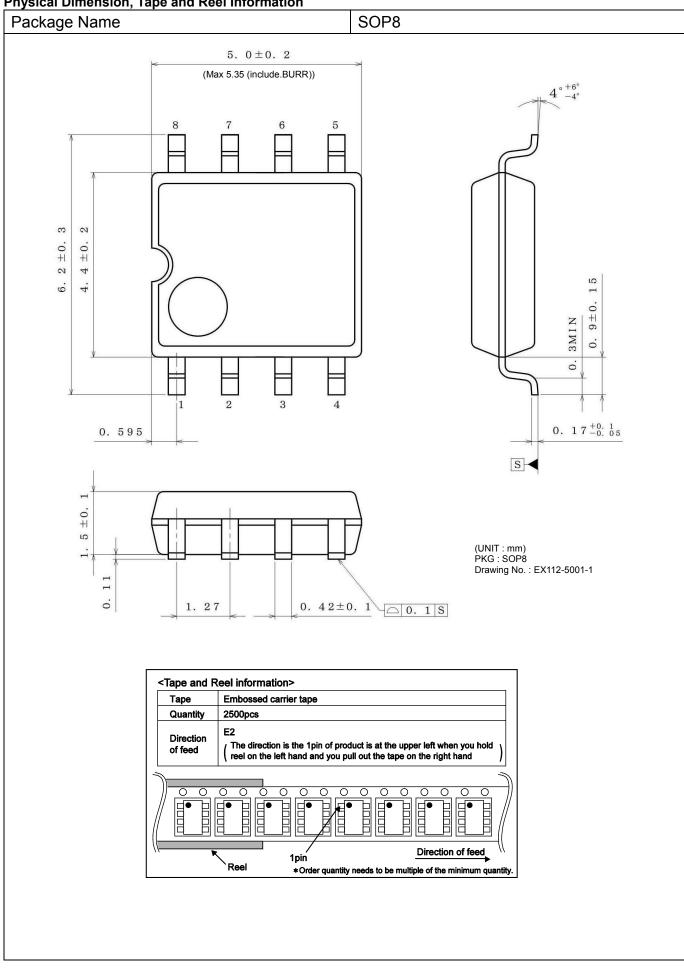
15. IC Handling

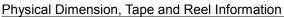
When pressure is applied to the IC through warp on the printed circuit board, the characteristics may fluctuate due to the piezo effect. Be careful with the warp on the printed circuit board.

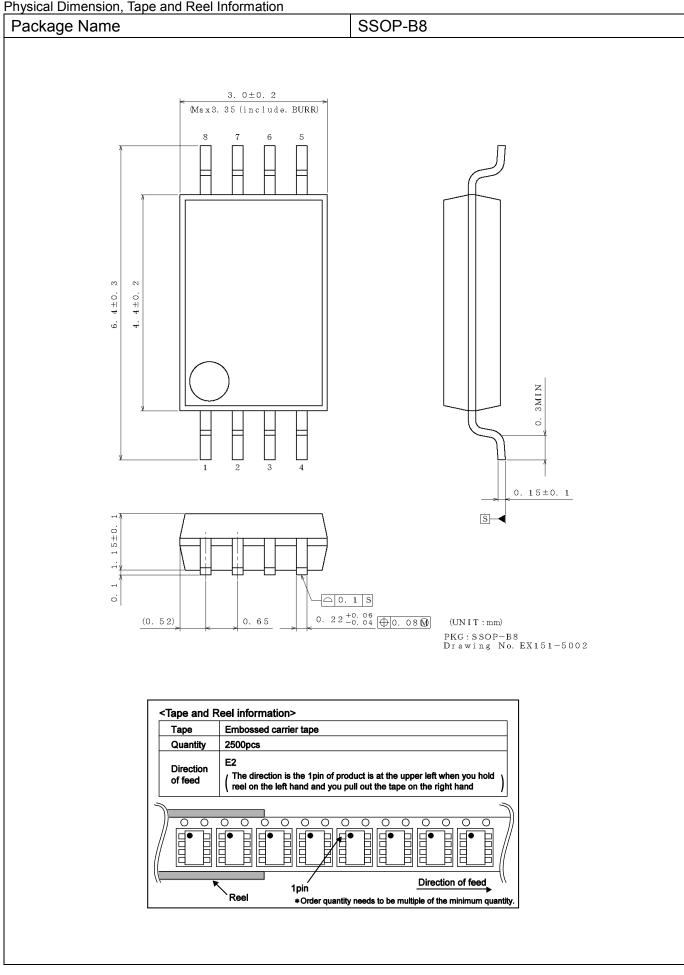
16. The IC Destruction Caused by Capacitive Load

The IC may be damaged when VCC terminal and VEE terminal is shorted with the charged output terminal capacitor. When IC is used as an operational amplifier or as an application circuit where oscillation is not activated by an output capacitor, output capacitor must be kept below 0.1µF in order to prevent the damage mentioned above.



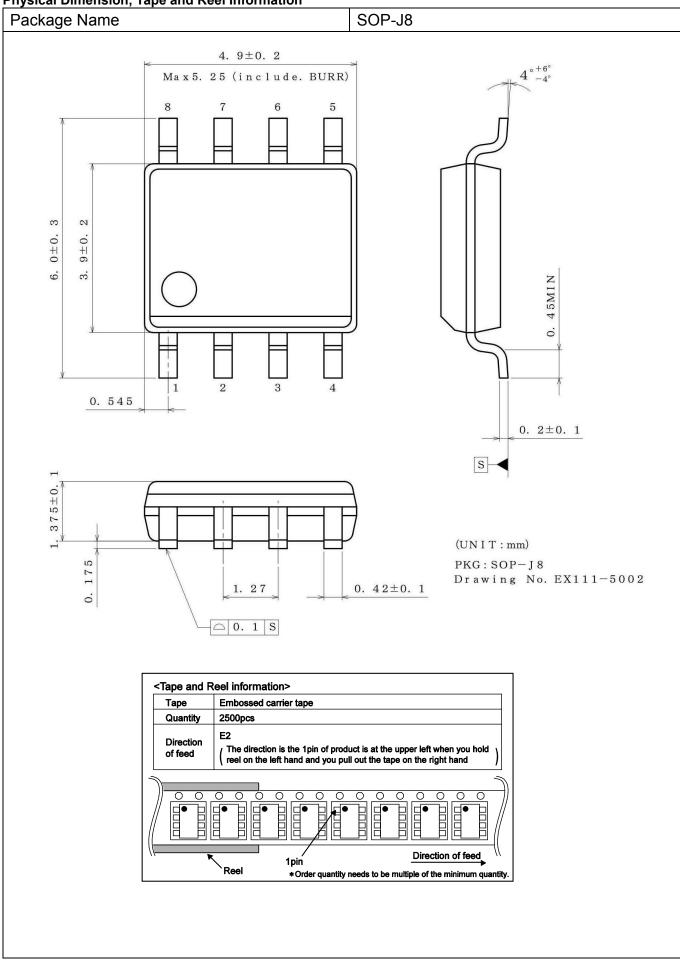






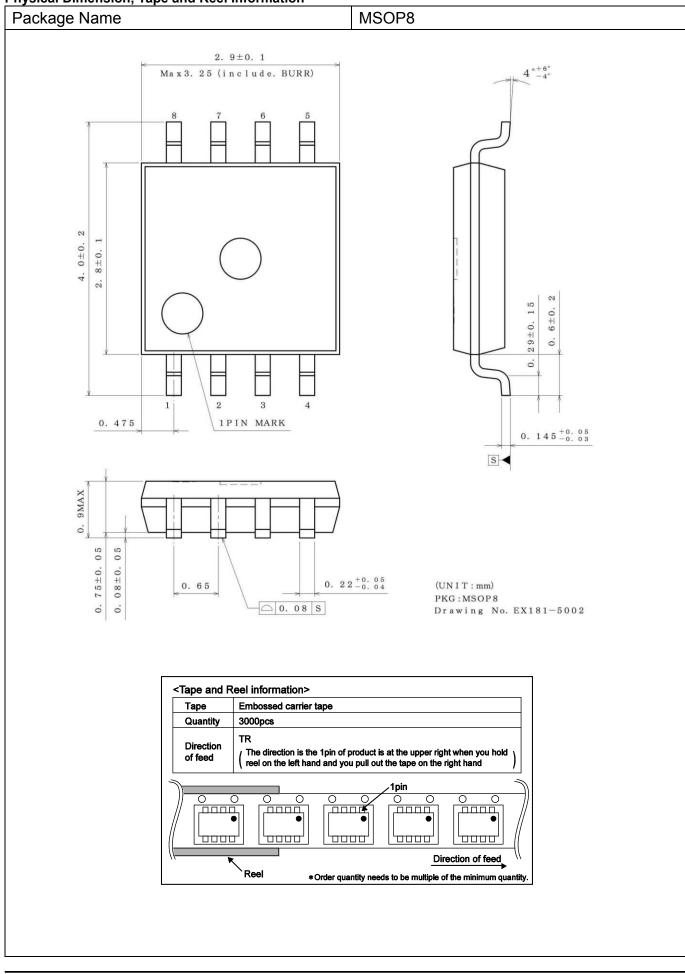
Datasheet





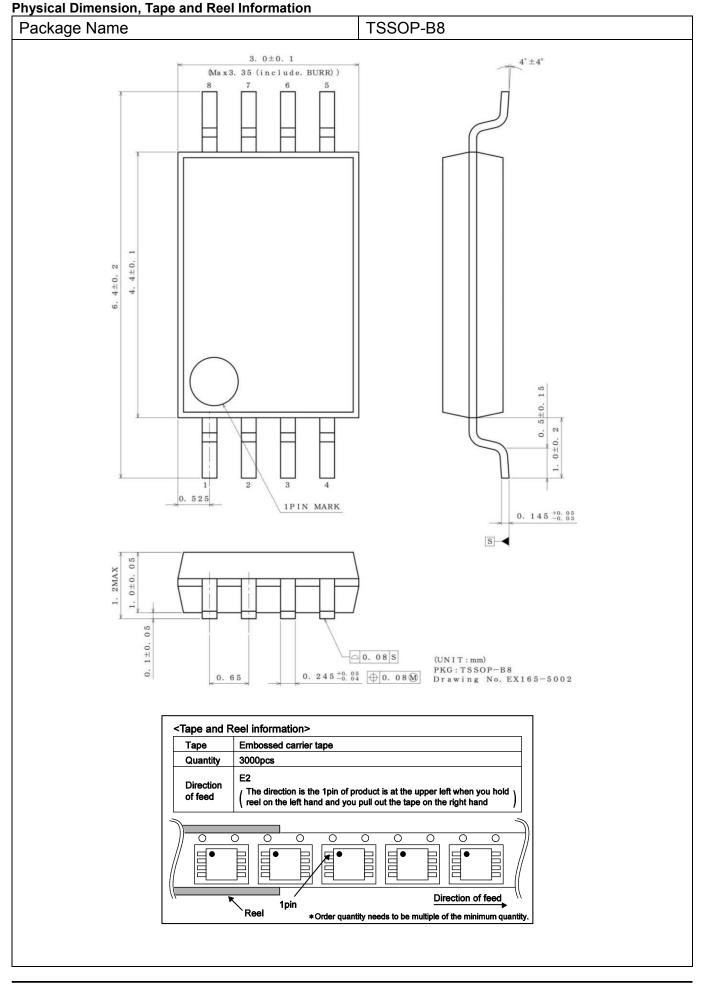
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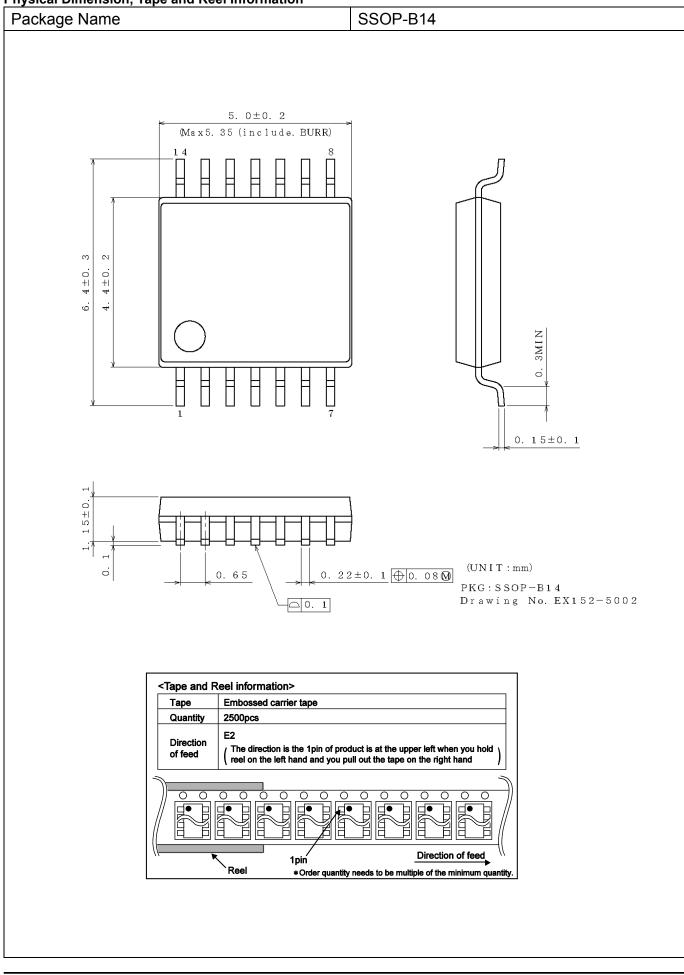


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Datasheet

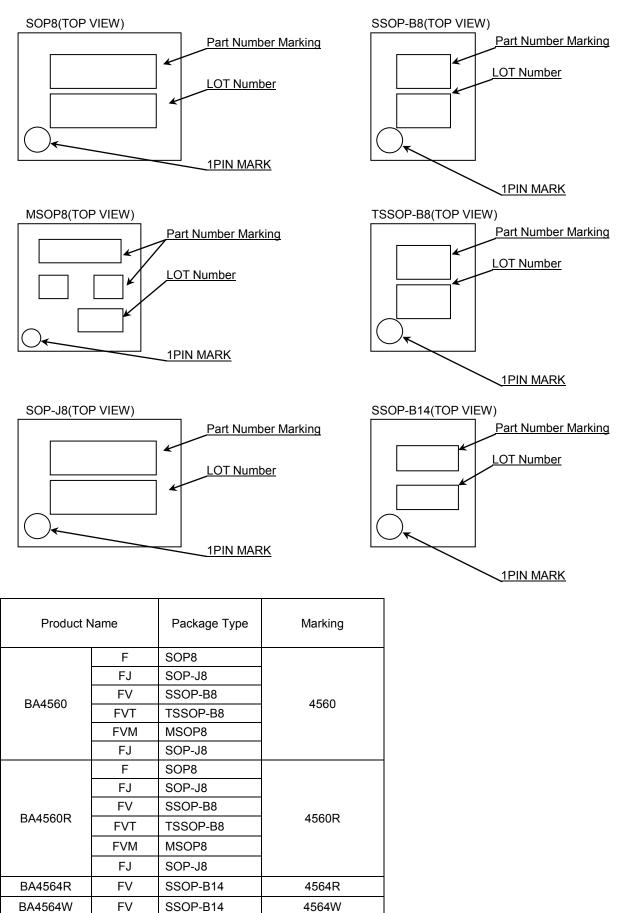






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Marking Diagrams



Revision History

Date	Revision	Changes		
10/May/2012	001	New Release		
07/Sep/2012	002	Added Line-up		
19/Nov/2014	003	Page.3 Absolute Maximum Ratings : Added Input Current		

Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	USA EU		
CLASSⅢ		CLASS II b	CLASSⅢ	
CLASSⅣ	CLASSⅢ	CLASSⅢ	CLASSI	

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

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